computers and word processors, and other various commercial displays. Plastic transparent substrates, as compared with glass substrates, are lightweight and less likely to be broken, but on the other hand, they are disadvantageous in that dust is electrostatically deposited on the surface thereof and, in addition, the hardness is so low that the scratch resistance is poor and, hence, scratches created by rubbing, scratching or the like deteriorate the transparency. Further, a problem common to transparent substrates is that viewing of visual information, such as objects, letters, or figures, through transparent substrates, or viewing of images from the reflective layer through the transparent substrate in mirrors causes outdoor daylight to be reflected from the surface of the transparent substrates, making it difficult to view internal visual information.

Page 6, last paragraph continuing to page 7, replace with:

Examples of ionizing radiation curing silicon compounds usable herein include organosilicon compounds, containing a plurality of groups capable of being reaction crosslinked upon exposure to an ionizing radiation, for example, polymerizable

double bond groups, having a molecular weight of not more than 5,000. This type of reactive organosilicon compounds includes polysilanes terminated on one end with a vinyl functional group, polysilanes terminated on both ends with a vinyl functional group, polysiloxanes terminated on one end with a vinyl functional group, polysiloxanes terminated on both ends with a vinyl functional group, and vinyl-functional polysilanes or vinyl-functional polysiloxanes obtained by reacting these compounds. Specific examples of reactive organosilicon compounds usable herein include the following compounds.

Page 8, last paragraph continuing on page 9, replace with the following:

A3

The hardcoat provided on the transparent conductive layer is a layer that has a hardness high enough to withstand scratching and is not significantly detrimental to the electrical conductivity. The hardcoat may be generally formed by coating. Reaction curing resins, reactive organosilicon compounds and the like usable in the formation of the conductive layer may also be used in the formation of the hardcoat. The amount of the

reactive organosilicon compound used may be in the above range (10 to 100% by weight). When the amount of the reactive organosilicon compound used is less than 10% by weight, the adhesion between the hardcoat layer and the low refractive layer provided on the hardcoat layer is unsatisfactory. As with the conductive layer, the hardcoat layer may be formed using only the ionizing radiation curing silicon compound (3) as the resin component. The coating method and the curing method may be the same as those described above in connection with the formation of the conductive layer. The term "hardcoat layer" used herein refers to a coat having a hardness of H or higher as measured by a pencil hardness test specified in JIS K 5400.

Page 10, replace the first full paragraph with:

A4

According to the present invention, bringing the refractive index of the hardcoat layer to higher than that of the low refractive layer can further lower the reflectance of the low reflective antistatic hardcoat film of the present invention.

Page 10, last paragraph continuing on page 11, replace with the following:

A5

Further, resins containing molecules or atoms as a high refractive component may be added to the reaction curing resin composition for the hardcoat layer. Molecules and atoms usable as the high refractive component include halogen atoms other than fluorine, sulfur, nitrogen, and phosphorus atoms, and aromatic rings. Methods usable for forming a hardcoat using the reaction curing resin composition comprising the above components include one that comprises dissolving or dispersing the above components in a suitable solvent to form a coating liquid, coating the coating liquid directly on the conductive layer and curing the coating, and one that comprises coating the coating liquid onto a release film, curing the coating, and transferring the cured coating onto the conductive layer with the said of a suitable adhesive. When the formation of the hardcoat layer by the transfer is contemplated, it is possible to use a method that comprises forming a low refractive layer described below on a release film, forming a hardcoat layer on the low refractive layer, and transferring both the layers onto the conductive

Cont. A5

layer. The thickness of the hardcoat layer thus formed is generally about 1 to 50 μm, preferably about 3 to 20 μm.

Page 12, last paragraph continuing on page 13, replace with the following:

A6

The additional layer may be formed by coating a desired coating liquid directly or indirectly on the transparent substrate film. When the hardcoat is formed by transfer onto the transparent substrate film, a method may be used that comprises coating a coating liquid for an additional layer (an adhesive layer or the like) onto a hardcoat previously provided on a release film, laminating the release film having thereon the hardcoat and the additional layer onto a transparent substrate film so that the coating on the release film faces the transparent substrate film, and then separating the release film, thereby transferring the hardcoat and the additional layer onto the transparent substrate film. A pressure-sensitive adhesive may be coated onto the underside of the low reflective antistatic film according to the present invention, and, in use, this low reflective antistatic film may be applied to such an object that

reflection and the deposition of dust caused by electrification should be prevented, for example, to polarizing elements.

Page 20, replace the paragraph after Table 2 with the following:

A7

Thus, according to the present invention, a low reflective antistatic film can be provided which, when used in various displays and the like to distinguish visual information, such as objects, letters, and figures through a transparent substrate or when used in viewing an image from a mirror through the transparent substrate from its reflective layer side, can prevent electrostatic deposition of foreign materials on the surface of the transparent substrate, has hardness high enough not to cause a deterioration in transparency due to a scratch created upon being rubbed, and can prevent reflection of outdoor daylight from the surface of the transparent substrate. The above film of the present invention can maintain the transparency on such a level that recognition of images viewed through the film is not hindered.